

|    | Type | L # | Hits | Search Text  | DBs  | Time Stamp       | Comments |
|----|------|-----|------|--|--|------------------|----------|
| 11 | BRS  | L11 | 9825 | (seed\$4 or Cu or copper) and (Ni or nickel or Au or gold or plat\$4 or electroplat\$4) and (UBM or metallurgy or underbump or (under adj bump)) | USPAT;<br>US-PGPUB;<br>EPO;<br>JPO;<br>DERWENT;<br>IBM-TDB | 2004/10/20 21:31 |          |
| 12 | BRS  | L12 | 2539 | 11 and (pad or bondpad or ((wir\$6 or bump or ball) near3 bond\$4))  | USPAT;<br>US-PGPUB;<br>EPO;<br>JPO;<br>DERWENT;<br>IBM-TDB | 2004/10/20 21:31 |          |
| 14 | BRS  | L14 | 2304 | 12 and (semiconductor or chip or die or IC or (integrated adj circuit))  | USPAT;<br>US-PGPUB;<br>EPO;<br>JPO;<br>DERWENT;<br>IBM-TDB | 2004/10/20 21:32 |          |